MSKSEMI 美森科













ESD

T

TSS

MOV

GDT

PIFD

L7812CD2T(MS)

Product specification





Three-terminal positive voltage

FEATURES

Maximum Output current IOM: 1.5 A

Output voltage Vo: 12V

Continuous total dissipation

P_D: 1.5 W (T_a = 25 °C) 15 W(T_c = 25 °C)

Reference News

PACKAGE OUTLINE		Marking	
MSKS SWI	1.IN 2.GND 3.OUT	MSKSEMI L7812CD2T CHN MS**	

ABSOLUTE MAXIMUM RATINGS (Operating temperature range applies unless otherwise specified)

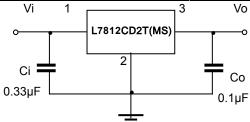
Parameter	Symbol	Value	Unit
Input Voltage	Vi	35	V
Thermal Resistance from Junction to Air	$R_{ heta JA}$	83.3	°C/W
Thermal Resistance from Junction to Case	R _{0JC}	8.33	°C/W
Operating Junction Temperature Range	T _{OPR}	0~+150	°C
Storage Temperature Range	T _{STG}	-55~+150	℃

ELECTRICAL CHARACTERISTICS AT SPECIFIED VIRTUAL JINCTION TEMPERATURE

(Vi=10V,lo=500mA,Ci=0.33 $\mu F,$ Co=0.1 $\mu F,$ unless otherwise specified)

Parameter	Symbol	Test conditions		Min	Тур	Max	Unit
0.10.10.010.00	14		25℃	11.64	12	12.36	V
Output voltage	Vo	7V≤V i≤20V, Io=5mA-1A, P≤15W	0-125℃	11.4	12	12.6	V
Load Regulation	△Vo	Io=5mA-1.5A	25℃		9	100	mV
		lo=250mA-750mA	25℃		4	50	mV
Line regulation	△Vo	7V≤V _i ≤25V	25℃		4	100	mV
		8V≤V _i ≤12V	25℃		1.6	50	mV
Quiescent Current	Iq		25℃		5	8	mA
Quiescent Current Change	△lq	7V≤V _i ≤25V	0-125℃		0.3	1.3	mA
		5mA≤l _O ≤1A	0-125℃		0.03	0.5	mA
Output Noise Voltage	V_N	10Hz≤f≤100KHz	25℃		42		μV
Output voltage drift	\triangle Vo/ \triangle T	I _O =5mA	0-125℃		-1.1		mV/℃
Ripple Rejection	RR	8V≤V _i ≤18V,f=120Hz	0-125℃	62	73		dB
Dropout Voltage	Vd	lo=1A	25℃		2		V
Output resistance	Ro	f=1KH _Z	0-125℃		10		mΩ
Short Circuit Current	Isc		25℃		230		mA
Peak Current	lpk		25℃		2.2		Α

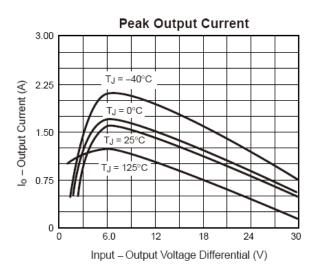
TYPICAL APPLICATION

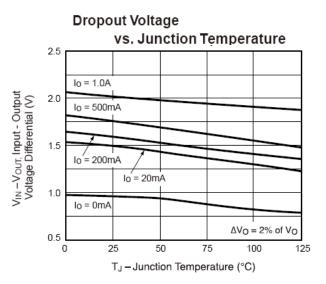


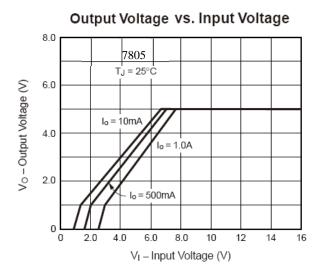
Note: Bypass capacitors are recommended for optimum stability and transient response and should be located as close as possible to the regulators.

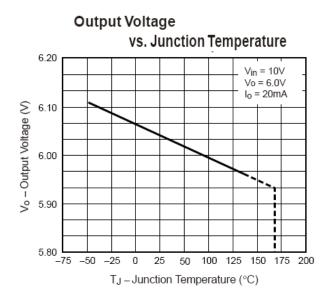


Typical Characteristics



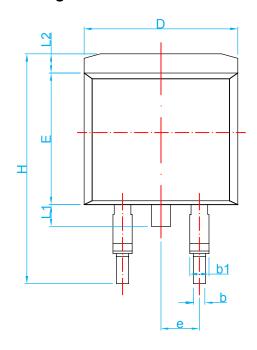


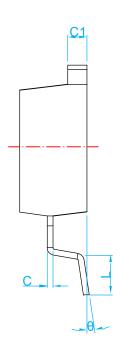


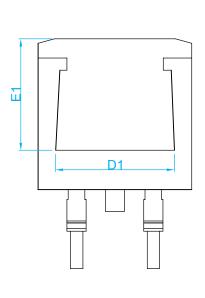


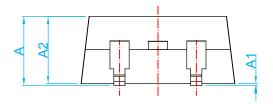


Package Outline Dimensions









Symbol	Dimensions in Millimeters		Dimensions in Inches		
Syllibol	Min	Max	Min	Max	
Α	4.06	5.08	0.160	0.200	
A1	0.00	0.25	0.000	0.010	
A2	4.06	4.83	0.160	0.190	
b	0.50	1.00	0.020	0.039	
b1	1.14	1.78	0.045	0.070	
С	0.33	0.74	0.013	0.029	
C1	1.14	1.67	0.045	0.066	
D	9.65	10.67	0.380	0.420	
D1	6.23		0.245		
Е	8.38	9.66	0.330	0.380	
E1	6.86		0.270		
Н	14.60	15.88	0.575	0.625	
е	2.54 TYP		0.100 TYP		
L	1.78	2.84	0.070	0.112	
L1	1.20	1.78	0.047	0.070	
L2	1.17	1.68	0.046	0.066	
θ	0°	8°	0°	8°	

REEL SPECIFICATION

P/N	PKG	QTY
L7812CD2T(MS)	TO-263	1000



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